

# 60V, 55A, 8.9mΩ N-channel Power Trench MOSFET

### JMTG100N06A

#### **Features**

- $\bullet \;\;$  Excellent  $R_{DS(ON)}$  and Low Gate Charge
- 100% UIS TESTED
- 100% ΔVds TESTED
- Halogen-free; RoHS-compliant
- Pb-free plating

#### **Applications**

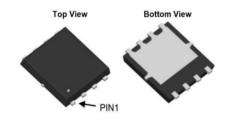
- Load Switch
- PWM Application
- Power Management

### **Product Summary**

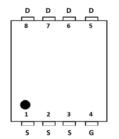
Parameters	Value	Unit
$V_{DSS}$	60	V
$V_{GS(th)\_Typ}$	1.5	V
$I_D(@V_{GS}=10V)$	55	Α
$R_{DS(ON)\_Typ}(@V_{GS}=10V$	7.7	mΩ
$R_{DS(ON)\_Typ}(@V_{GS}=4.5V$	8.9	mΩ



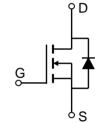




PDFN5x6-8L



**Pin Assignment** 



**Schematic Diagram** 

#### **Ordering Information**

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMTG100N06A	60N04	1	Tape&Reel	PDFN5x6-8L	2500	25000

#### **Absolute Maximum Ratings** (@ T<sub>C</sub> = 25°C unless otherwise specified)

Symbol	Parameter		Value	Unit
$V_{DS}$	Drain-to-Source Voltage		60	V
$V_{GS}$	Gate-to-Source Voltage		±20	V
I <sub>D</sub>	Continuous Drain Current	$T_C = 25$ °C	55	A
ıD	Continuous Drain Current	$T_C = 100$ °C	39	
$I_{DM}$	Pulsed Drain Current (1)		Refer to Fig.4	А
E <sub>AS</sub>	Single Pulsed Avalanche Energ	y <sup>(2)</sup>	118	mJ
$P_{D}$	Dower Discipation	$T_C = 25$ °C	134	W
' D		$T_C = 100$ °C	54	vv
$T_{J}, T_{STG}$	Junction & Storage Temperature F	Range	-55 to 150	°C

#### **Thermal Characteristics**

Symbol	Parameter	Max	Unit	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	42	°C/W	
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.9	°C/VV	



### **Electrical Characteristics** (T<sub>J</sub> = 25°C unless otherwise specified)

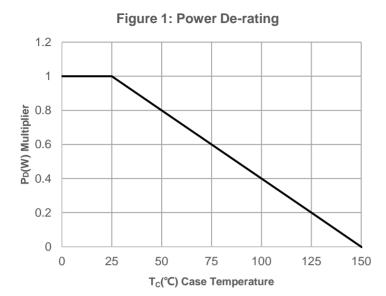
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics	_l		,		,
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	60	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 60 \text{ V}, \ V_{GS} = 0 \text{ V}$	-	-	1.0	μА
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	racteristics			•		
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.1	1.5	2.0	V
D	Static Drain-Source ON-Resistance <sup>(4)</sup>	$V_{GS} = 10V, I_D = 20A$	-	7.7	10.0	mΩ
$R_{DS(ON)}$	Static Drain-Source ON-Resistance	$V_{GS} = 4.5V, I_D = 15A$	-	8.9	11.5	mΩ
Dynami	c Characteristics					
$R_{g}$	Gate Resistance	f = 1MHz	-	2.2	-	Ω
$C_{iss}$	Input Capacitance	., ., ., ., .,	-	4160	-	pF
C <sub>oss</sub>	Output Capacitance	$V_{GS} = 0V, V_{DS} = 30V,$ $f = 1MHz$	-	184	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	148	-	pF
$Q_g$	Total Gate Charge	V 0 40V	-	77	-	nC
$Q_{gs}$	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 30V, I_{D} = 20A$	-	14	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge	= V <sub>DS</sub> = 50V, I <sub>D</sub> = 25A	-	13	-	nC
Switchi	ng Characteristics					
$t_{d(on)}$	Turn-On DelayTime		-	11	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 30V$	-	28	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	$I_D = 20A, R_{GEN} = 3\Omega$	-	66	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	15	-	ns
Body D	iode Characteristics					
$I_S$	Maximum Continuous Body Diode Forward	Current	-	-	55	Α
I <sub>SM</sub>	Maximum Pulsed Body Diode Forward Curi	rent	-	-	220	А
V <sub>SD</sub>	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 20A$	-		1.2	V
trr	Body Diode Reverse Recovery Time	1 20A di/d+ 400A/	-	26	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 20A$ , di/dt = 100A/us	-	35	-	nC

Notes:

- 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- $2.\;E_{AS}\;condition:\;Starting\;T_{J}=25C,\;V_{DD}=30V,\;V_{G}=10V,\;R_{G}=25ohm,\;L=0.5mH,\;I_{AS}=21.7A,\;V_{DD}=0V\;during\;time\;in\;avalanche.$
- 3.  $R_{\theta JA}$  is measured with the device mounted on a 1inch  $^{\!2}$  pad of 2oz copper FR4 PCB.
- 4. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  0.5%.



# **Typical Performance Characteristics**



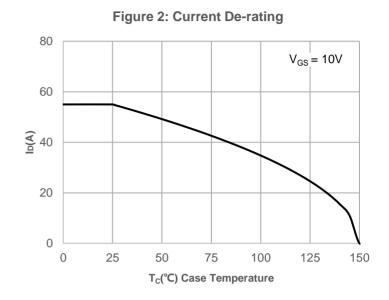
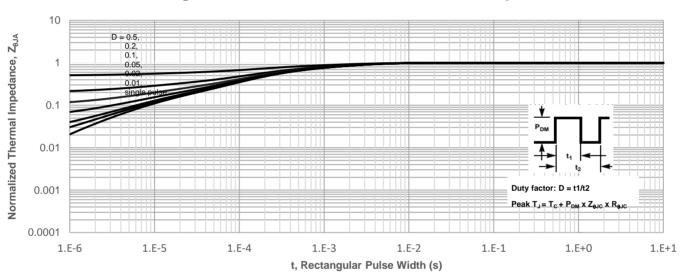


Figure 3: Normalized Maximum Transient Thermal Impedance

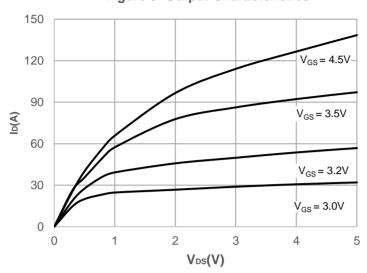


**Figure 4: Peak Current Capacity** 10000  $V_{GS} = 10V$ For TEMPERATURES ABOVE IDM Peak Current(A) 25°C DERATE PEAK CURRENT 1000 150*-Tc* 125 100 Single Pulse 10 1.E-5 1.E-3 1.E-4 1.E-2 1.E-1 1.E+0 1.E+1 1.E-6 t, Rectangular Pulse Width (s)



# **Typical Performance Characteristics**

**Figure 5: Output Characteristics** 



**Figure 6: Typical Transfer Characteristics** 

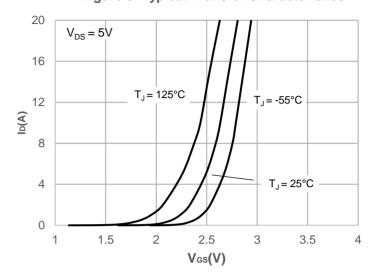


Figure 7: On-resistance vs. Drain Current

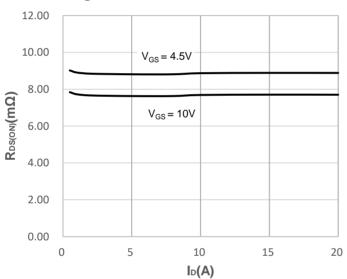
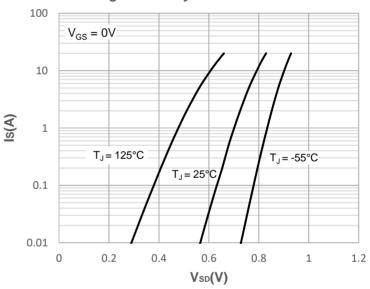


Figure 8: Body Diode Characteristics



**Figure 9: Gate Charge Characteristics** 

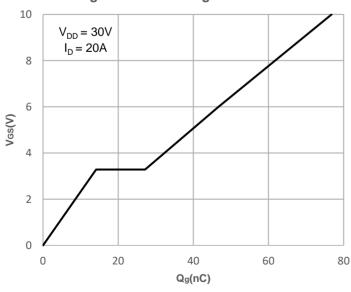
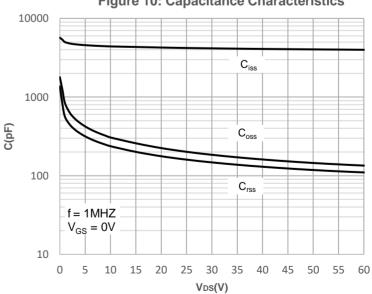


Figure 10: Capacitance Characteristics





# **Typical Performance Characteristics**

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

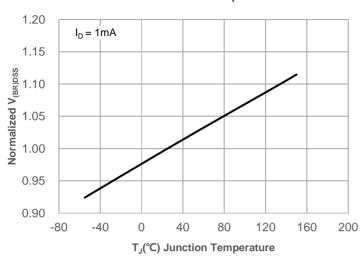


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

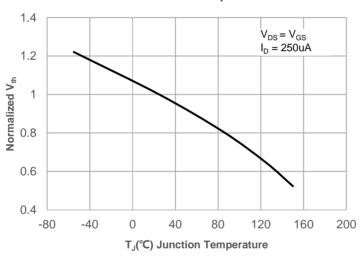


Figure 15: Maximum Safe Operating Area

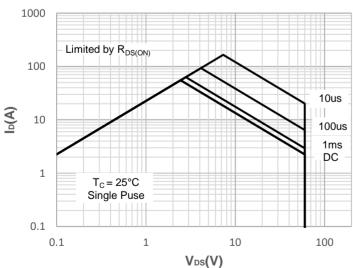
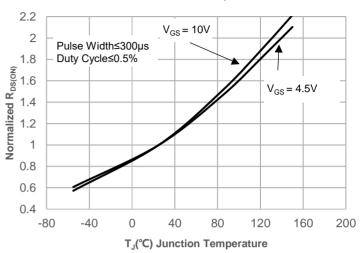
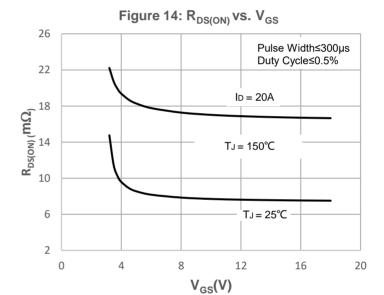


Figure 12: Normalized on Resistance vs. Junction Temperature







### **Test Circuit**

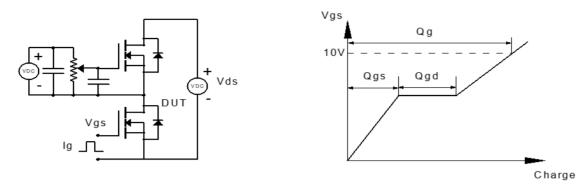


Figure 1: Gate Charge Test Circuit & Waveform

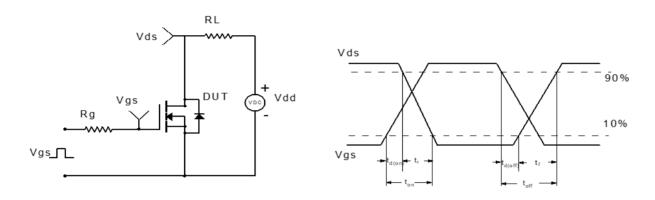


Figure 2: Resistive Switching Test Circuit & Waveform

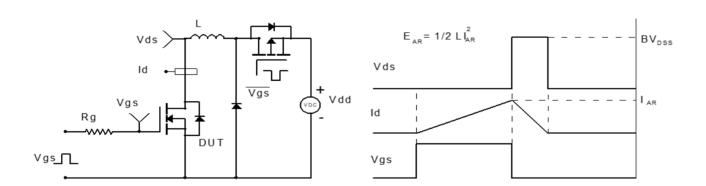


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

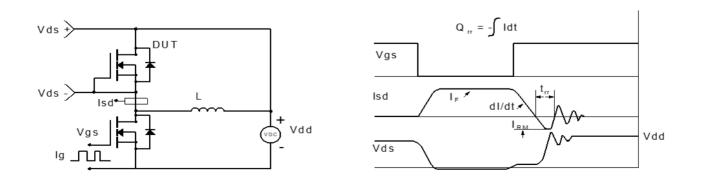
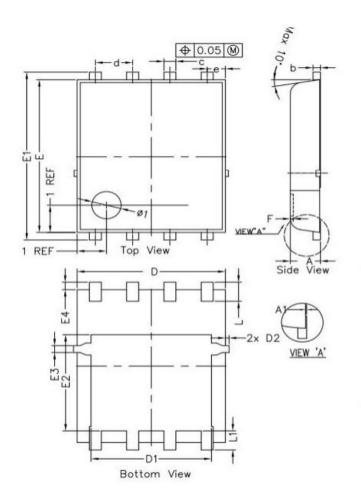


Figure 4: Diode Recovery Test Circuit & Waveform



### Package Mechanical Data- PDFN5x6-8L



3		FLIA	IENSION IN	MM	DIME	NSION IN I	NCHES	
	SYMBOLS	MIN	NOM	MAX	MIN	NOM	MAX	
	* A	0.900	1.000	1.100	0.035	0.039	0.043	
	A1	0.000		0.050	0.000	****	0.002	
	b	0.246	0.254	0.312	0.010	0.010	0.012	
	* c	0.310	0.410	0.510	0.012	0.016	0.020	
	d		1.27 BSC	(C)		0.050 BSC		
	* D	4.950	5.050	5.150	0.195	0.199	0.203	
	D1	4.000	4.100	4.200	0.157	0.161	0.165	
	* D2			0.125			0.005	
	e		0.62 BSC		0.024 BSC			
	* E	5.500	5.600	5.700	0.217	0.220	0.224	
	* E1	6.050	6.150	6.250	0.238	0.242	0.246	
	E2	3.425	3.525	3.625	0.135	0.139	0.143	
	E3	0.150	0.250	0.350	0.006	0.010	0.014	
	* E4	0.175	0.275	0.375	0.007	0.011	0.015	
	F	-	-	0.100	-	-	0.004	
	* L	0.500	0.600	0.700	0.02	0.02	0.03	
	L1	0.600	0.700	0.800	0.02	0.03	0.03	

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